



Product specification

The **DCSRG3-080305** piezoelectric stack consists of multiple chips which are bonded via epoxy. It offers a maximum displacement of 5.5 μm . The red wire of the electrode serves as the positive terminal (+), and the black wire is the negative terminal (-).



DCSRG3-080305

Performance Parameters

Drive Voltage Range	-30~150 V	Capacitance	730nF \pm 15%
Displacement (Free Stroke) at 150 V	5.5 μm \pm 15%	Dissipation Factor	<2.3%
Hysteresis	<15%	Resonant Frequency	170kHz
Stiffness	327 N/ μm	Blocking Force at 150 V	1800N
Curie Temperature	230 $^{\circ}\text{C}$	Operating Temperature	-25 ~ 130 $^{\circ}\text{C}$
Product Size	Outside diameter : 8.3mm	Outer Dimensions	Outside diameter : 9.7 \pm 0.2mm
	Inside diameter : 3.0mm		Inside diameter : 3.0 \pm 0.2mm
	Altitude : 5.0mm		Altitude : 5.0 \pm 0.1mm

- All specifications are quoted at 25 $^{\circ}\text{C}$, unless otherwise stated.
- The displacement may vary slightly for different loads, and the maximum displacement occurs when used with the recommended load.

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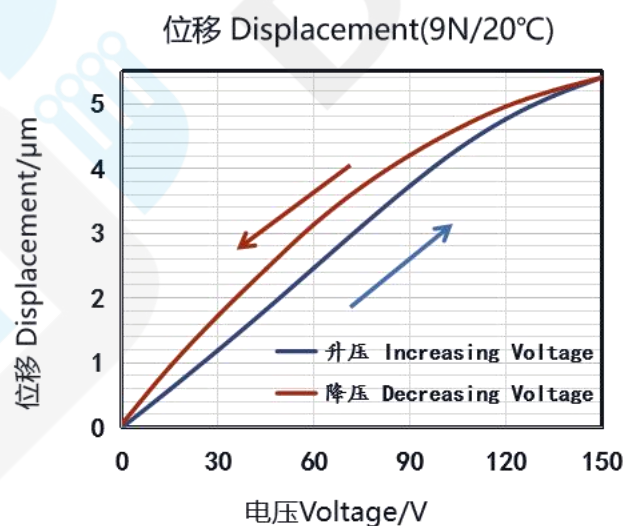


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Product Size



Performance Curve



- These temperature rises were measured after applying a sine-wave drive voltage ranging from 0 to 150V at the specified frequency for 10 minutes.

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Matters Needing Attention

1. Storage Conditions & Precautions:

Temperature: $<50^{\circ}\text{C}$, Humidity: $<40\%\text{Rh}$. Avoid impact and compression. Store in vacuum-sealed bags for long-term preservation. When not in use, connect to a resistive discharge ($\geq 100\text{k}\Omega$) or short-circuit (for low-capacitance ceramics).

2. Operating Conditions & Precautions:

Temperature: Maximum operating temperature $\leq 130^{\circ}\text{C}$ (preferably $<60^{\circ}\text{C}$). Add heat dissipation measures if temperature exceeds 80°C .

Humidity: $<50\%\text{Rh}$. In high-humidity environments, preheat at low voltage before use to avoid creepage discharge.

Dust Avoidance: Dust adhesion on ceramic surfaces may reduce insulation resistance.

Clearance: Maintain a gap $>1.6\text{mm}$ between ceramics and other conductors.

Safety: Do not immerse piezoelectric stacks in organic solvents or expose to flammable gases/liquids.

3. Assembly Precautions:

Polarity: Red wire = positive (+), black wire = negative (-). Reverse polarity may cause mechanical failure.

Handling: Handle with care to avoid impact. Wear gloves to prevent oil contamination.

Fit Tolerance: Assemble with clearance fit first, then tighten. Avoid interference fit to prevent ceramic compression.

Electrostatic Protection: Maintain $>1.6\text{mm}$ gap between ceramics and metal parts to avoid static discharge.

Adhesive Bonding: Ensure flat bonding surfaces and remove excess glue to minimize contamination.

Soldering: Limit contact time under high temperature to <1 second to protect ceramics and coatings.

High-Temperature Assembly: Control temperature $<120^{\circ}\text{C}$ to prevent depolarization, adhesive failure, or coating damage.

4. Preload Instructions:

Load Application: Apply external load to the center of the stack or distribute uniformly on the

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mounting surface. Ensure contact surfaces are flat and smooth.

Force Direction: Piezoelectric stacks can only withstand axial forces. Shear or torsional forces may cause mechanical failure.

Preload Force: Preload should not exceed 40% of maximum blocking force, and its direction must align with the motion axis to minimize shear stress.

